selectively removing portions of the conductive sheet thereby producing a plurality of substantially rigid, elongated posts protruding parallel to one another from the first surface of the support substrate, each post having a base surface and a top surface, wherein each base surface is disposed on the support substrate, the top surfaces being remote from the support substrate and substantially coplanar with respect to one another.

C2 3. (Twice Amended) The method as claimed in claim 2, wherein each said post has a direction of elongation and at least one edge extending along the post in said direction of elongation.

C3 5. (Twice Amended) The method as claimed in claim 4, wherein each said post has at least a direction of elongation and one edge extending along the post in said direction of elongation.

8. (Twice Amended) The method as claimed in claim 7, wherein said selectively removing step is performed so that each of said posts has an exposed surface, the method further comprising plating a conductive layer to the exposed surface of each of said posts.

9. (Amended) The method as claimed in claim 1, wherein the step of selectively removing comprises:

providing etch-resistant portions to a surface of the conductive sheet remote from the support substrate; and

C4 etching the conductive sheet, the etch-resistant portions being substantially unaffected by the etching process.

10. (Amended) The method as claimed in claim 9, wherein the providing etch resistant portions step includes:

applying a photoresist layer to the conductive sheet;

selectively developing the photoresist layer to form etch resistant portions and remaining portions; and

removing remaining portions of the photoresist layer.

11. (Amended) The method as claimed in claim 1, further comprising:

providing a microelectronic device having a plurality of bond pads; and

electrically connecting said bond pads to said posts.

C4 12. The method as claimed in claim 11, wherein said step of providing said microelectronic device is performed so that said microelectronic device overlies a second surface of said support substrate, said second surface of said support substrate being remote from said posts, the method further comprising disposing a compliant layer between the second surface of the substrate and the microelectronic device.

13. (Amended) The method as claimed in claim 12, further comprising soldering a portion of each post remote from said support substrate to a contact on a printed circuit board.

15. (Amended) The method as claimed in claim 11, wherein said support substrate has a second surface the step of electrically connecting includes:

C5 providing a plurality of conductive vias extending from the first surface of the support substrate to the second surface of the support substrate, each via positioned beneath and in electrical contact with one post;

connecting each bond pad to a respective post through a respective conductive via.

16. (Amended) The method as claimed in claim 15, wherein the connecting step includes providing brazing buttons each extending from one via and coupling each one of said brazing buttons to one of said bond pads on a said microelectronic element.

Insert new claims 48-50, as follows:

48. (New) The method as claimed in claim 11 further comprising providing electrically conductive leads on said support substrate so that said leads are electrically connected to said posts, said step of connecting said bond pads of said microelectronic device and said posts including connecting said bond pads and said leads.

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49. (New) The method as claimed in claim 48 wherein said step of providing electrically conductive leads includes providing leads formed from an etch-resistant metal on said first surface of said support substrate.

50. (New) The method as claimed in claim 49 wherein said step of providing said etch-resistant metal is performed before said step of coupling said conductive sheet to said first surface of said support substrate.